

*Fuller E. Callaway, Jr. Manufacturing Research Center*

*Georgia Institute of Technology*

## ***Manufacturing Seminar Series***

**Professor Bahgat Sammakia**

Director and Professor of Mechanical Engineering

**Thursday, February 26, 2009**

MARC Auditorium @ 11:00 a.m.

**"An overview of the Research at the Small Scale Systems**

**Integration and Packaging (S<sup>3</sup>IP); A New York Center of Excellence."**

### **Abstract**

The S<sup>3</sup>IP Center of Excellence was formed in 2005 and is one of six New York State Centers that are focused on National Research Initiatives including Bioinformatics, Environmental and Energy Systems, Photonics and Microsystems, Nanoelectronics, Wireless and Information Technologies and Small Scale Systems Integration and Packaging (S3IP). The vision for the S3IP Center is "To create and enable new electronics applications and devices that improve the way people live and interact with their surroundings". The center is currently focused on electronics packaging, flexible electronics, autonomous solar power and Green Data Centers. This talk will give an overview of the research conducted at the center and will then focus on the current thrust in flexible electronics. The talk will also highlight the nature of the collaborative research between BU and its partner academic institutes, industry and government.

### **Biography**

Bahgat Sammakia is a professor of Mechanical Engineering and the Director of the New York Center of Excellence in the area of Small Scale Systems Integration and Packaging at Binghamton University. He received his Bachelor of Science degree in Mechanical Engineering in 1977, from the University of Alexandria in Egypt and the master's and doctorate degrees in mechanical engineering in 1980 and 82 respectively from the State University of New York at Buffalo. His research work was in the areas of natural convection heat transfer. After graduating from SUNY, Bahgat worked at the University

of Pennsylvania as a postdoctoral fellow for 1 year before joining IBM from 1984 to 1998. He has been at Binghamton University since 1998. Bahgat is an ASME fellow and is a member of the IEEE and is the editor of the Journal of Electronic Packaging, Transactions of the ASME. Bahgat's current research interests are thermal management of electronic systems and flexible electronics.

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